



12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN#20250710001.1

**Qualification of RFAB as an additional Fab site option,
Die Revision, Datasheet, BOM options & TI Mexico as
additional Assembly site option for select devices**

Change Notification / Sample Request

Date: July 11, 2025

To: Mouser PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

Texas Instruments requires acknowledgement of receipt of this notification within 60 days of the date of this notice. Lack of acknowledgement of this notice within 60 days constitutes acceptance and approval of this change. If samples or additional data are required, requests must be received within 60 days of this notification.

The changes discussed within this PCN will not take effect any earlier than the proposed first ship date on Page 3 of this notification, unless customer agreement has been reached on an earlier implementation of the change.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice or to provide acknowledgement of this PCN, you may contact your local Field Sales Representative or the change management team.

For sample requests or sample related questions, contact your local Field Sales Representative.

TI values customer engagement and feedback related to TI changes. Customers should contact TI if there are questions or concerns regarding a change notification.

Sincerely,

Change Management Team
SC Business Services

20250710001.1
Attachment: 1

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, you have recently purchased these devices. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
SN74LVC74ADR	NULL
SN74LVC02ADRG4	NULL
SN74LVC125ADRG4	NULL
SN74LVC74ADRE4	NULL
SN74LVC02ADR	NULL
SN74LVC74APWRE4	NULL
SN74LVC74ARGYR	SN74LVC74ARGYR
SN74LVC08ADRG4	NULL
SN74LVC74APWR	NULL
SN74LVC74APWRG4	NULL

Technical details of this Product Change follow on the next page(s).

PCN Number:	20250710001.1	PCN Date:	July 11, 2025
Title:	Qualification of RFAB as an additional Fab site option, Die Revision, Datasheet, BOM options & TI Mexico as additional Assembly site option for select devices		
Customer Contact:	Change Management Team	Dept:	Quality Services
Proposed 1st Ship Date:	October 09, 2025	Sample requests accepted until:	September 09, 2025*

*Sample requests received after September 09, 2025 will not be supported.

Change Type:

<input checked="" type="checkbox"/>	Assembly Site	<input checked="" type="checkbox"/>	Design	<input type="checkbox"/>	Wafer Bump Material
<input type="checkbox"/>	Assembly Process	<input checked="" type="checkbox"/>	Data Sheet	<input type="checkbox"/>	Wafer Bump Process
<input checked="" type="checkbox"/>	Assembly Materials	<input type="checkbox"/>	Part number change	<input checked="" type="checkbox"/>	Wafer Fab Site
<input type="checkbox"/>	Mechanical Specification	<input type="checkbox"/>	Test Site	<input checked="" type="checkbox"/>	Wafer Fab Material
<input checked="" type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process	<input checked="" type="checkbox"/>	Wafer Fab Process

PCN Details

Description of Change:

Texas Instruments is pleased to announce the qualification of RFAB as an additional Fab site option & TI Mexico as additional Assembly site options for the devices listed below.

Current Fab Site			Additional Fab site		
Current Fab Site	Process	Wafer Diameter	Additional Fab site	Process	Wafer Diameter
FFAB	ASLNONC 10	200mm	RFAB	LBC7	300mm

The die was also changed as a result of the process change.

Construction differences are as follows:

Group 1 device

	Current site		Additional site
	MLA	MLA(New)	MEX
Wire bond diam/type	0.96mil Cu	0.8mil Cu	0.8mil Cu

Group 2 device

	Current BOM	Additional BOM
Wire bond diam/type	0.96mil Cu	0.8mil Cu

The datasheets will be changing as a result of the above mentioned changes. The datasheet change details can be reviewed in the datasheet revision history. The links to the revised datasheets are available in the table below.



SN54LVC02A, SN74LVC02A

SCAS280T – JANUARY 1993 – REVISED DECEMBER 2024

Changes from Revision S (May 2024) to Revision T (December 2024)

Page

- Updated R_{0JA} values: D = 86 to 127.8, all values in °C/W.....5



SN54LVC74A, SN74LVC74A

SCAS287W – JANUARY 1993 – REVISED DECEMBER 2024

Changes from Revision V (May 2024) to Revision W (December 2024)

Page

- Updated R_{0JA} values: D = 93.7 to 127.8, DB = 107.3 to 140.4, NS = 90.3 to 123.8, PW = 121.7 to 150.8, RGY = 54.9 to 92.1; Updated D, DB, NS, PW, and RGY packages for R_{0JC}(top), R_{0JB}, Ψ_{JT}, Ψ_{JB}, and R_{0JC}(bot), all values in °C/W.....5



TEXAS
INSTRUMENTS

SN54LVC08A, SN74LVC08A

SCAS283W – JANUARY 1993 – REVISED JULY 2024

Changes from Revision V (May 2024) to Revision W (July 2024)

Page

- Updated thermal values for D package from R_{0JA} = 98.6 to 127.8, R_{0JC}(top) = 56.0 to 81.9, R_{0JB} = 53.3 to 84.4, Ψ_{JT} = 16.4 to 39.6, Ψ_{JB} = 53.0 to 83.9, R_{0JC}(bot) = N/A, all values in °C/W 6



TEXAS
INSTRUMENTS

SN74LVC125A

SCAS290T – JANUARY 2015 – REVISED SEPTEMBER 2024

Changes from Revision S (May 2024) to Revision T (September 2024)

Page

- Updated thermal values for D package from R_{0JA} = 86 to 127.8, all values in °C/W 5



TEXAS
INSTRUMENTS

SN74LVC10A

SCAS284Q – JANUARY 1993 – REVISED AUGUST 2024

Changes from Revision P (May 2024) to Revision Q (August 2024)

Page

- Updated R_{0JA} values: D = 86 to 127.8, NS = 76 to 123.8, PW = 113 to 150.8, R_{GY} = 47 to 92.1, all values in °C/W 5

Product Folder	Current Datasheet Number	New Datasheet Number	Link to full datasheet
SN74LVC02A	SCAS280S	SCAS280T	http://www.ti.com/product/SN74LVC02A
SN74LVC74A	SCAS287V	SCAS287W	http://www.ti.com/product/SN74LVC74A
SN74LVC08A	SCAS283V	SCAS283W	http://www.ti.com/product/SN74LVC08A
SN74LVC125A	SCAS290S	SCAS290T	http://www.ti.com/product/SN74LVC125A
SN74LVC10A	SCAS284P	SCAS284Q	http://www.ti.com/product/SN74LVC10A

Qual details are provided in the Qual Data Section.

Test coverage, insertions, conditions will remain consistent with current testing.

Reason for Change:

Supply Continuity

Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):

None

Impact on Environmental Ratings

Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings.

RoHS

REACH

Green Status

IEC 62474

<input checked="" type="checkbox"/> No Change			
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Changes to product identification resulting from this PCN:

**Fab Site
Information:**

Chip Site	Chip Site Origin Code (20L)	Chip Site Country Code (21L)	Chip Site City
FFAB	TID	DEU	Freising
RFAB	RFB	USA	Richardson

Die Rev:

Current

New

Die Rev [2P]	Die Rev [2P]
B, K	A

Assembly Site Information:

	Assembly Site	Assembly Site Origin (22L)	Assembly Country Code (23L)	Assembly City
	TI Malaysia	MLA	MYS	Kuala Lumpur
	TI Mexico	MEX	MEX	Aguascalientes

Sample product shipping label (not actual product label):



Group 1 Product Affected: (Fab, Die rev, Assembly site)

SN74LVC02ADR	SN74LVC08ADRG4	SN74LVC125ADRE4	SN74LVC74ADR.B
SN74LVC02ADR.A	SN74LVC08ADRE4	SN74LVC125ADRG4.B	SN74LVC74ADRE4
SN74LVC02ADR.B	SN74LVC08ADRG4.B	SN74LVC74ADR	
SN74LVC02ADRG4	SN74LVC125ADRG4	SN74LVC74ADR.A	

Group 2 Product Affected: (Fab, Die rev, BOM update)

SN74LVC10APWRG4.A	SN74LVC74APWRG4.B	SN74LVC10APWRG4.B
SN74LVC74APWRG4	SN74LVC10APWRG4	SN74LVC74APWRE4

Group 1 Qualification Report

Approve Date 07-JANUARY -2025

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: SN74LVC74ADR	Qual Device: SN74LVC02ADR	QBS Reference: SN3257QDYYRQ1	QBS Reference: LM2903BQDRQ1	QBS Reference: TL2843BD-8	QBS Reference: SN74LVC02ABQAR	QBS Reference: SN74LVC74ABQAR	QBS Reference: SN74AC08QDRG4Q1	QBS Reference: SN74LVC11ADR
HAST	A2	Biased HAST	130C/85%RH	96 Hours	-	-	3/231/0	1/77/0	1/77/0	-	-	1/77/0	-
UHAST	A3	Autoclave	121C/15psig	96 Hours	-	-	3/231/0	-	1/77/0	-	-	-	-
UHAST	A3	Unbiased HAST	130C/85%RH	96 Hours	-	-	-	1/77/0	-	-	-	1/77/0	-
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	-	-	3/231/0	1/77/0	3/231/0	-	-	1/77/0	-
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	-	-	3/135/0	-	1/77/0	-	-	-	-
HTSL	A6	High Temperature Storage Life	175C	500 Hours	-	-	-	-	-	-	-	1/45/0	-
HTOL	B1	Life Test	150C	300 Hours	-	-	3/231/0	3/231/0	-	-	-	-	-
ELFR	B2	Early Life Failure Rate	125C	48 Hours	-	-	-	1/800/0	-	-	-	-	-
ELFR	B2	Early Life Failure Rate	150C	24 Hours	-	-	3/2400/0	-	-	-	-	-	-
SD	C3	PB Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	-	-	1/15/0	1/15/0	-	-	-	-	-
SD	C3	PB-Free Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	-	-	1/15/0	1/15/0	-	-	-	-	-
PD	C4	Physical Dimensions	Cpk>1.67	-	-	-	3/30/0	1/10/0	-	-	-	1/10/0	-
ESD	E2	ESD CDM	-	1500 Volts	-	-	1/3/0	1/3/0	-	-	-	-	-

ESD	E2	ESD CDM	-	250 Volts	1/3/0	1/3/0	-	-	1/3/0	1/3/0	1/3/0	-	1/3/0
ESD	E2	ESD CDM	-	500 Volts	-	-	-	-	-	-	-	-	1/3/0
ESD	E2	ESD HBM	-	1000 Volts	-	-	-	-	1/3/0	1/3/0	1/3/0	-	-
ESD	E2	ESD HBM	-	2000 Volts	-	-	1/3/0	1/3/0	-	-	-	-	-
LU	E4	Latch-Up	Per JESD78	-	-	-	1/6/0	1/6/0	1/3/0	1/3/0	1/3/0	-	-
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	1/30/0	1/30/0	-	-	1/30/0	1/30/0	1/30/0	-	1/30/0
CHAR	E5	Electrical Distributions	Cpk>1.67 Room, hot, and cold	-	-	-	3/90/0	3/90/0	-	-	-	1/30/0	-

QBS: Qual By Similarity, also known as Generic Data

Qual Device SN74LVC74ADR is qualified at MSL1 260C

Qual Device SN74LVC02ADR is qualified at MSL1 260C

Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours

The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>
TI Qualification ID: R-CHG-2408-066

Group 2 Qualification Report

Approve Date 07-MAY -2024

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: SN74LVC125APWR	Qual Device: SN74LVC02APWR	QBS Reference: SN3257QDYYRQ1	QBS Reference: SN74HC574QPWRQ1	QBS Reference: SN74LVC11AWBQARQ1	QBS Reference: SN74LVC125AWBQARQ1	QBS Reference: SN74LVC11APWRQ1	QBS Reference: SN74LVC02AWBQARQ1	QBS Reference: SN74LVC132APWR
HAST	A2	Biased HAST	130C/85%RH	96 Hours	-	-	3/231/0	3/231/0	1/77/0	-	1/77/0	-	-
UHAST	A3	Autoclave	121C/15psig	96 Hours	-	-	3/231/0	3/231/0	-	-	-	-	-
UHAST	A3	Unbiased HAST	130C/85%RH	96 Hours	-	-	-	-	1/77/0	-	1/77/0	-	-
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	-	-	3/231/0	3/231/0	1/77/0	-	1/77/0	-	-
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	-	-	3/135/0	3/135/0	1/45/0	-	1/45/0	-	-
HTOL	B1	Life Test	125C	1000 Hours	-	-	-	3/231/0	1/77/0	-	-	-	-
HTOL	B1	Life Test	150C	300 Hours	-	-	3/231/0	-	-	-	-	-	-
ELFR	B2	Early Life Failure Rate	125C	48 Hours	-	-	-	3/2400/0	-	-	-	-	-
ELFR	B2	Early Life Failure Rate	150C	24 Hours	-	-	3/2400/0	-	-	-	-	-	-
SD	C3	PB Solderability	Precondition w/155C Dry Bake (4 hrs +/- 15 minutes)	-	-	-	1/15/0	1/15/0	-	-	-	-	-
SD	C3	PB-Free Solderability	Precondition w/155C Dry Bake (4 hrs +/- 15 minutes)	-	-	-	1/15/0	1/15/0	1/15/0	-	-	-	-
PD	C4	Physical Dimensions	Cpk>1.67	-	-	-	3/30/0	3/30/0	1/10/0	-	1/10/0	-	-
ESD	E2	ESD CDM	-	1500 Volts	-	-	1/3/0	1/3/0	1/3/0	1/3/0	1/3/0	1/3/0	-
ESD	E2	ESD CDM	-	250 Volts	-	1/3/0	-	-	-	-	-	-	1/3/0
ESD	E2	ESD CDM	-	500 Volts	-	-	-	1/3/0	1/3/0	1/3/0	1/3/0	1/3/0	-
ESD	E2	ESD HBM	-	2000 Volts	-	-	1/3/0	1/3/0	1/3/0	1/3/0	1/3/0	1/3/0	-
LU	E4	Latch-Up	Per JESD78	-	-	-	1/6/0	1/6/0	1/6/0	1/6/0	1/6/0	1/6/0	-
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	1/30/0	1/30/0	-	-	-	-	-	-	1/30/0
CHAR	E5	Electrical Distributions	Cpk>1.67 Room, hot, and cold	-	-	-	3/90/0	3/90/0	3/90/0	1/30/0	1/30/0	1/30/0	-

QBS: Qual By Similarity

Qual Device SN74LVC125APWR is qualified at MSL1 260C

Qual Device SN74LVC02APWR is qualified at MSL1 260C

Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours

The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles
Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

TI Qualification ID: R-CHG-2403-037

In performing change qualifications, Texas Instruments follows integrated circuit industry standards in performing defect mechanism analysis and failure mechanism-based accelerated environmental testing to ensure wafer fab process, assembly process and product quality and reliability. As encouraged by these standards, TI uses both product-specific and generic (family) data in qualifying its changes. For devices to be categorized as a 'product qualification family' for generic data purposes, they must share similar product, wafer fab process and assembly process elements. The applicability of generic data (also known at TI as Qualification by Similarity (QBS)) is determined by the Reliability Engineering function following these industry standards. Generic data is shown in the qualification report in columns titled "QBS Process" (for wafer fab process), "QBS Package" (for assembly process) and "QBS Product" (for product family).

For questions regarding this notice, e-mails can be sent to the Change Management team or your local Field Sales Representative.

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